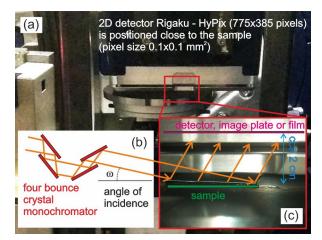
MUNIDepartment of Condensed Matter Physics Application Example SCI Matter Physics X-ray diffraction imaging of silicon carbide wafers

This application list shows visualization of strain and surface damage in silicon carbide wafers using x-ray diffraction. The experimental technique is a natural extension of the classical xray diffraction topography method. The x-ray topography uses film as a detector. The usage of digital area detectors instead of film allows us to collect a series of images with respect to the angle of incidence; in fact diffracted intensity curve dependence (so-called rocking curve) is measured in every detector pixel. The rocking curves is usually a curve with a single diffraction peak. The collected data can be evaluated by means of various quantities; we have used angular peak position, peak width, maximal and integral intensity.

The rocking curve imaging is performed in asymmetric grazing incidence diffraction which allows us for large irradiated area.

Fig. 1 shows an experimental setup for the rocking curve imaging. The detector is positioned close to the sample.



▲ Fig. 1: Photography of the actual setup (a). Scheme of the beam path in monochromator (b) and sample (c).

[1] M. Meduňa, O. Caha, E. Choumas, F. Bressan, and H. von Känel, submitted to J. Appl. Crystallography.

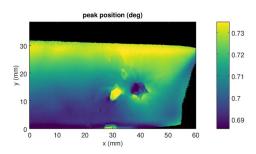
MORE INFO

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EXAMPLES

The experiments presented in figures 2 and 3 were performed in diffraction $11\overline{2}6$ at angle of incidence of 0.7 deg.





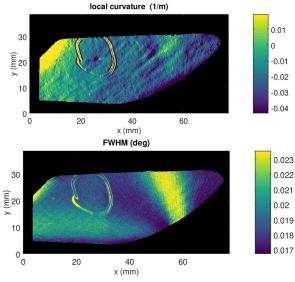


 Fig. 3: Single area of SiC wafer. Top panel: peak position derivative with respect to x axis (local curvature) showng crack in wafer. Bottom: peak width as FWHM showing polishing scratches.

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